

0.5A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

Features

- Low Forward Voltage Drop
- Guard Ring Construction for Transient Protection
- High Conductance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen- and Antimony-Free. "Green" Device (Notes 3 & 4)**
- **Qualified to AEC-Q101 Standards for High-Reliability**

Mechanical Data

- Case: SOD123
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity: Cathode Band
- Lead Free Plating (Matte Tin Finish Annealed over Alloy 42 Lead-Frame). Solderable per MIL-STD-202, Method 208 ⑥③
- Weight: 0.01 grams (Approximate)

SOD123



Top View

Ordering Information (Note 5)

Part Number	Case	Packaging
B0520LW-7-F	SOD123	3000/Tape & Reel
B0520LWQ-7-F	SOD123	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Product manufactured with Date Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ fire retardants.
 5. For packaging details, see <http://www.diodes.com>.

Marking Information



SD = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: F = 2018)
 M = Month (ex: 9 = September)

Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	...	2018	2019	2020	2021	2022	2023	2024
Code	J	K	L	M	N	P	R	...	F	G	H	I	J	K	L

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	20	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_R		
RMS Reverse Voltage	$V_{R(RMS)}$	14	V
Average Rectified Output Current @ $T_L = +90^\circ\text{C}$	I_O	0.5	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	5.5	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P_D	410	mW
Typical Thermal Resistance Junction to Ambient (Note 6)	$R_{\theta JA}$	244	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +125	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Test Conditions
Minimum Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	20	V	$I_R = 250\mu\text{A}$
Maximum Forward Voltage Drop	V_{FM}	0.300	V	$I_F = 0.1\text{A}, T_J = +25^\circ\text{C}$
		0.385		$I_F = 0.5\text{A}, T_J = +25^\circ\text{C}$
		0.220		$I_F = 0.1\text{A}, T_J = +100^\circ\text{C}$
		0.330		$I_F = 0.5\text{A}, T_J = +100^\circ\text{C}$
Maximum Leakage Current (Note 8)	I_{RM}	75	μA	$V_R = 10\text{V}, T_J = +25^\circ\text{C}$
		250		$V_R = 20\text{V}, T_J = +25^\circ\text{C}$
	I_{RM}	5.0	mA	$V_R = 10\text{V}, T_J = +100^\circ\text{C}$
		8.0		$V_R = 20\text{V}, T_J = +100^\circ\text{C}$
Typical Total Capacitance	C_T	170	pF	$V_R = 0\text{V DC}, f = 1\text{MHz}$

- Notes:
6. Device mounted on FR-4 PC board, 2" x 2", 2 oz. Copper, single sided, Cathode pad dimensions 0.75" x 1.0", Anode pad dimensions 0.25" x 1.0".
 7. Pulse Test: Pulse width = 300 μs , Duty Cycle \leq 2%.
 8. No purposefully added lead. Halogen and Antimony Free.

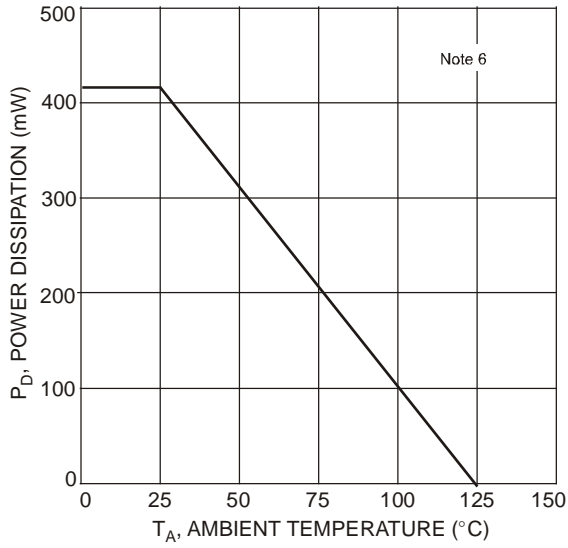


Fig. 1 Forward Power Dissipation

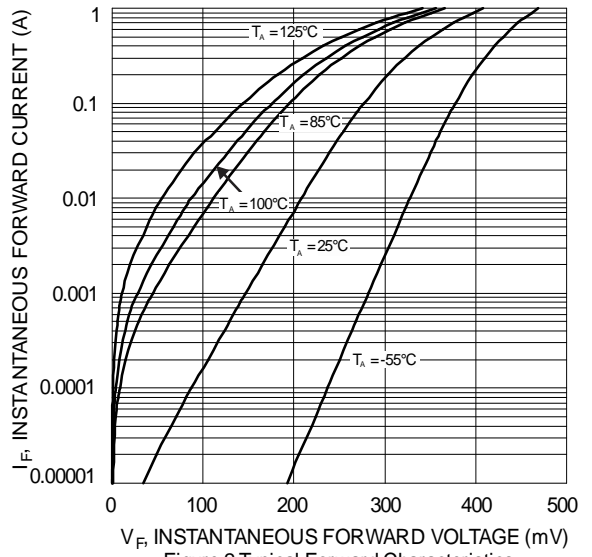


Figure 2 Typical Forward Characteristics

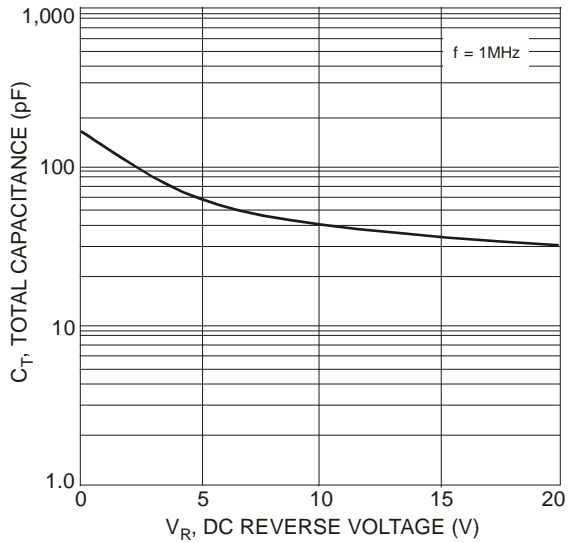


Fig. 3 Total Capacitance vs. Reverse Voltage

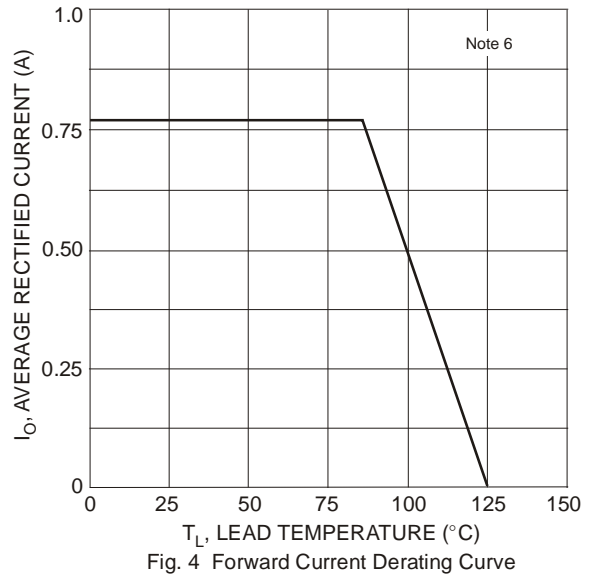
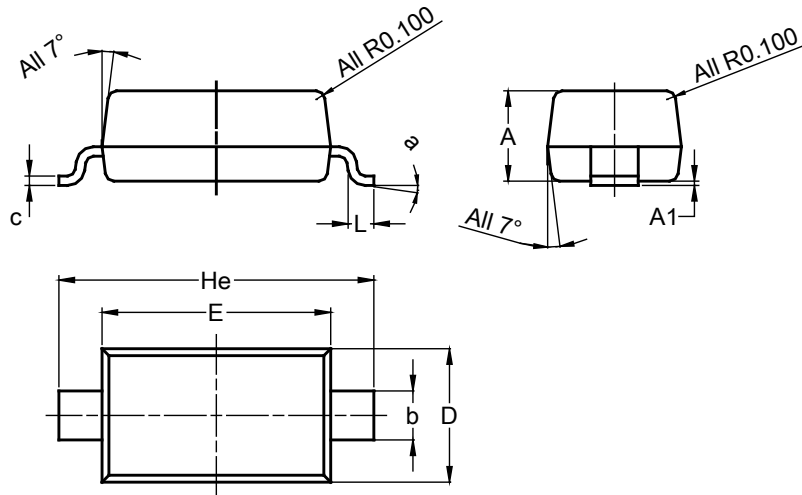


Fig. 4 Forward Current Derating Curve

Package Outline Dimensions

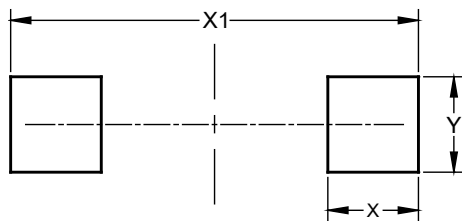
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



SOD123			
Dim	Min	Max	Typ
A	1.00	1.35	1.05
A1	0.00	0.10	0.05
b	0.52	0.62	0.57
c	0.10	0.15	0.11
D	1.40	1.70	1.55
E	2.55	2.85	2.65
He	3.55	3.85	3.65
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
X	0.900
X1	4.050
Y	0.950

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